MAR 3 1 2004	، بر <u>د</u>	Sheet	1	of	1
44-	u/	SHEEL	<u></u>	_ ''' _	

9	. 4/	
B/O Form PTO-1449	Atty. Docket Number	Serial Number
	CHAN3228/EM	10/699,839
U.S. Department of Commerce Patent and Trademark Office	Applicant	
Patent and Trademark Office	Edward Y. CHANG et. al.	
Information Disclosure Statement by Applicant	Filing Date	Group
	November 4, 2003	Unassigned

U.S. Patent Documents

Examiner Initial	Document Number	Date	Patentee/Applicant	Class	Subclass	Filing Date if Appropriate
MK	5,959,308	09/28/1999	Shichijo et. al.	_		01/29/1993
MA	5,879,962	03/09/1999	DePuydt et. al.			12/13/1995
MAX	5,473,174	12/05/1995	Ohsawa	_		11/28/1994
14/4	5,308,444	05/03/1994	Fitzgerald, Jr. et. al.			05/28/1993
MAT	5,438,951	08/08/1995	Tachikawa et. al.			12/20/1993
MAX	5,238,869	08/24/1993	Shichijo et. al.			07/27/1992
MA	5,183,776	02/02/1993	Lee			08/03/1989
utt	5,141,893	08/25/1992	lto et. al.			02/20/1991
MA	6,291,321	09/18/2001	Fitzgerald			03/09/1999
MA	6,107,635	08/22/2000	Palathingal		 	06/11/1998

Foreign Patent Documents

Examiner Initial							Tran	slation
	Document Number	Publication Date	Country/Agency	Class	Subclass	Yes	No	
				·				

Other Documents (Including Author, Title, Date, Pertinent Pages, Place of Publication, Etc.)

— (110)	Decaments (mercaning reason) - the property of
MA	J. A. Carlin et. al., Impact of GaAs buffer thickness on electronic quality of GaAs grown on graded Ge/GeSi/Si substrates, April 2000, American Institute of Physics, Applied Physics Letters, Vol. 76, No. 14, pp. 1884-1886.
UA	R. D. Bringans et. al., <i>Use of ZnSe as an interlayer for GaAs growth on Si</i> , July 1992, American Institute of Physics, Applied Physics Letters, Vol. 61, No. 2, pp. 195-197.
UN	J. Arokiaraj et. al., High-quality GaAs on Si substrate by the epitaxial lift-off technique using SeS ₂ , December 1999, American Institute of Physics, Applied Physics Letters, Vol. 75, No. 24, pp. 3826-3828.
litt	C. Kadow et. al., Subpicosecond carrier dynamics in low-temperature grown GaAs on Si substrates, October 1999, American Institute of Physics, Applied Physics Letters, Vol. 75, No. 17, pp. 2575-2577.
MH	Y. R. Xing et. al., Growth of high quality gallium arsenide on HF-etched silicon (001) by chemical beam epitaxy, April 1993, American Institute of Physics, Applied Physics Letters, Vol. 62, No. 14, pp. 1653-1655.
ut	Michael Y. Frankel et. al., Integration of low-temperature GaAs on Si substrates, January 1993, American Institute of Physics, Applied Physics Letters, Vol. 62, No. 3, pp. 255-257.

•		·					_
Examiner	March	won	Date Considered	56/	14/	05	
	1						

EXAMINER: Initial if citation is considered, whether or no t citation is in conformance with MPEP 609; Draw a line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

		, OITE	Tes I								
		TIM O B					Sheet	<u>1</u> of	1		
B/O Form F	TO-144	tment of Commerce BAD d Trademark Office	Atty. Oocket Numb		Serial N						
		Sec.	CHA	N3228/REF	<u>. </u>	10	0/699,839				
U.S Pa	6. Depar stent an	tment of Commerce BAD d Trademark Office	Applicant Edward V CHA	NG of al							
		sure Statement by Applicant	Edward Y. CHANG et al. Filing Date Group								
, ,,			-	mber 4, 2003		2818					
				ent Documents							
Examinar Initial		Document Number	Date	Patentee/Applicant		Class	Subclass	Filing I Appro	Date if priate		
		·									
			1								
		·	Foreign P	atent Documents							
Examiner Initial		Document Number	Publication Date	Country/Agency		Class	Subclass	Trans Yes	slation No		
MA		092120501	28/07/2003	Taiwan (English Abstra	ict)						
MA		092120502	28/07/2003	Taiwan (English Abstra	ict)		<u> </u>				
	Othe	r Documents (Including	Author, Title,	Date, Pertinent Page	s, Place	of Pub	lication, l	tc.)			
	-										
						<u></u>					
<u> </u>	<u> </u>										
Examiner		ALL MAN DIE	1000	Date Considered	Al.	114	-/25				

EXAMINER: Initial if citation is considered, whether or no traction is in conformance with MPEP 609; Drew a line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.